Date Created : **2007/10/10**
Date Issued On : **2007/11/09**
PCN# : **Q3073208-A**

DESIGN/PROCESS CHANGE NOTIFICATION -- FINAL

This Final PCN cover the die attach change only

This is to inform you that a design and/or process change will be made to the following product(s). This notification is for your information and concurrence.

If you require data or samples to qualify this change, please contact **Fairchild Semiconductor within 30 days of receipt of this notification.**

Updated process quality documentation, such as FMEAs and Control Plans, are available for viewing upon request.

If you have any questions concerning this change, please contact:

Technical Contact:
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PCN Originator:
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Implementation of change:
Expected 1st Device Shipment Date: 2007/12/10

Earliest Year/Work Week of Changed Product: 0750

Change Type Description: Die Attach Material

Description of Change (From): Change die attach epoxy, Hitachi EN4620K

Description of Change (To): Die attach epoxy, Henkel QMI-519

Reason for Change : Die attached epoxy standardization for all Samsung's Roughen uPPF lead frame

Qual/REL Plan Numbers : Q20070253

Qualification :

All reliability tests outlined in Q20060253 ,Q20070280 and Q20070117 qualification plan were completed successfully with no failure and meet the requirements for release. As such, MLP 8x8 (FDMF8700, FDMF8704, FDMF8705 as the qualification vehicle), MLP 6X6 (FDMF6700) and Q20070117 (FDMS9620S) with POR stated in the qualification plan is qualified.

Results/Discussion

Test: (Autoclave)

Lot	Device	96-HOURS	Failure Code
Q20070253AAACLVA	FDMF8704	0/77	
Q20070253BAACLVA	FDMF8700	0/77	
Q20070253CAACLVA	FDMF8705	0/77	

Test: -65C, 150C (Temperature Cycle)

Lot	Device	100-CYCLES	500-CYCLES	Failure Code
Q20070253AATMCL1A	FDMF8704	0/77		
Q20070253AATMCL1A	FDMF8704		0/77	
Q20070253BATMCL1A	FDMF8700	0/77		
Q20070253BATMCL1A	FDMF8700		0/77	
Q20070253CATMCL1A	FDMF8705	0/77		
Q20070253CATMCL1A	FDMF8705		0/77	

Test: 130C (Highly Accelerated Stress Test)

Lot	Device	96-HOURS	Failure Code
Q20070253AAHAST1A	FDMF8704	0/77	
Q20070253BAHAST1A	FDMF8700	0/77	
Q20070253CAHAST1A	FDMF8705	0/77	

Test: MSL(1), PKG(Small), PeakTemp(260c), Cycles(3) (Precondition)

Lot	Device	Results	Failure Code
Q20070253AAPCNL1AA	FDMF8704	0/231	
Q20070253BAPCNL1AA	FDMF8700	0/231	
Q20070253CAPCNL1AA	FDMF8705	0/231	

Product Id Description : FDMF8700, FDMF8705, FDMF6700 and FDMS9620S

Affected FSIDs :

FDMF8700	FDMF8705	FDMS9620S